

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (currently amended) A manufacturing method of a circuit substrate, in which an electronic circuit is formed on a surface of a base member by a solution jetting device, the manufacturing method comprising:

~~jetting liquid drops of a solution which is supplied into~~ providing a nozzle for the solution jetting device having a discharge port with an inner diameter of 0.1 μ m to 100 μ m ~~and;~~

supplying a solution into the nozzle of the solution jetting device, wherein the solution includes a plurality of fine particles adapted to form an electronic circuit by melting and sticking to one another, and a dispersant for dispersing the fine particles[[,]];

jetting liquid drops of the solution from the discharge port of the nozzle toward the surface of the base member by applying a voltage of an arbitrary waveform to the solution ~~to charge~~ so that the solution is electrically charged; and

exposing the jetted liquid drops received on the surface of the base member to light or heat to make the fine particles melt and stick to one another.

2. (currently amended) The manufacturing method of claim 1[[;]], wherein an average diameter of the fine particles is lower than or equal to 100nm.

3. (currently amended) The manufacturing method of claim 1[[;]], wherein the fine particles are made of a conductive material.

4. (currently amended) The manufacturing method of claim 1[[:]], wherein the fine particles are made of a semi-conductive material.

5. (currently amended) The manufacturing method of claim 1[[:]], wherein the fine particles are made of an insulating material or a dielectric material.

6. (currently amended) The manufacturing method of claim 1[[:]], wherein an inner diameter of the discharge port is smaller than or equal to 30 μ m.

7. (currently amended) The manufacturing method of claim 1[[:]], wherein an inner diameter of the discharge port is smaller than 20 μ m.

8. (currently amended) The manufacturing method of claim 1[[:]], wherein an inner diameter of the discharge port is smaller than or equal to 8 μ m.

9. (currently amended) The manufacturing method of claim 1[[:]], wherein an inner diameter of the discharge port is smaller than or equal to 4 μ m.

10. (currently amended) A manufacturing method of a circuit substrate, in which an electronic circuit is formed on a surface of a base member by a solution jetting device, the manufacturing method comprising:

~~jetting liquid drops of a solution which is supplied into~~ providing a nozzle for the solution

jetting device having a discharge port with an inner diameter of 0.1 μ m to 100 μ m ~~and~~;

supplying a solution into the nozzle of the solution jetting device, wherein the solution includes a plurality of adhesion particles adapted for adhering fine particles to form an electronic circuit by melting and sticking the fine particles to one another, and a dispersant for dispersing the adhesion particles[[,]];

jetting liquid drops of the solution from the discharge port of the nozzle toward the surface of the base member by applying a voltage of an arbitrary waveform to the solution ~~to~~ charge so that the solution is electrically charged; ~~and~~

scattering the fine particles on the jetted liquid drops received on the surface of the base member to adhere the fine particles to the adhesion particles;

removing fine particles which are not adhering to the adhesion particles among the scattered fine particles, from the surface of the base member; and

exposing the surface of the base member to light or heat to make the fine particles melt and stick to one another.

Claims 11 to 17 (cancelled)